



## Patent

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JUN 19 1971  
TECHNOLOGY CENTER

Andideh, E. et al.

U.S. Serial No: 09/436,092

Examiner: McDonald, S.

Filed: November 8, 1999

Art Unit: 3723

For: POLISH PAD WITH  
NON-UNIFORM GROOVE DEPTH  
TO IMPROVE WAFER POLISH RATE  
UNIFORMITY

Assistant Commissioner for Patents  
Washington, D.C. 20231

## AMENDMENT AND RESPONSE

Dear Sir:

This is in response to the Office Action mailed September 27, 2000. Applicant respectfully requests the Examiner to enter the following amendments and consider the following remarks.

**FIRST CLASS CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage in an envelope addressed to the Assistant Commissioner of Patents, Washington, D.C. 20231

on January 11, 2001

Date of Deposit

**Teresa Edwards**

Name of Person Mailing Correspondence

Tenzo Edwards  
Signature

Date January 11, 2001